

**EAST Search History****EAST Search History (Prior Art)**

| Ref # | Hits | Search Query  | DBs   | Default Operator | Plurals | Time Stamp          |
|-------|------|---|---|------------------|---------|---------------------|
| S1    | 1    | ("20070278278").PN.   | US-PGPUB;<br>USPAT; USOCR   | OR               | OFF     | 2009/10/06<br>10:20 |
| S2    | 10   | JP-05167241-\$ DID. OR JP-07230872-\$ DID. OR JP-2001244030-\$ DID. OR JP-2001244640-\$ DID. OR JP-200463373-\$ DID.  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ              | ON      | 2009/10/06<br>10:34 |
| S3    | 4    | JP-5167241-\$ DID. OR JP-2001244030-\$ DID. OR EP-1133003-\$ DID. OR US-20020022398-\$ DID. OR JP-200463373-\$ DID.   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ              | ON      | 2009/10/06<br>10:39 |
| S4    | 2    | JP-7230872-\$ DID. OR JP-2001244640-\$ DID.   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ              | ON      | 2009/10/06<br>10:40 |
| S5    | 12   | US-2005006-\$ DID. OR US-5006285-\$ DID. OR US-5167241-\$ DID. OR JP-2001244030-\$ DID. OR EP-1133003-\$ DID. OR US-20020022398-\$ DID. OR JP-200463373-\$ DID. OR US-2672005-\$ DID. | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ              | ON      | 2009/10/06<br>10:42 |
| S6    | 355  | (228/135).CCLS.   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2009/10/07<br>17:11 |

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| S7  | 523 | (molded interconnect device)  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/07<br>17:23 |
| S8  | 431 | S7 and (connector or conduct\$3 or solder or mask or ligh beam or shield) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/07<br>17:24 |
| S9  | 523 | (molded interconnect device)  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>10:23 |
| S10 | 273 | S9 and (solder\$3 or mask or ligh beam or shield)                         | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>10:23 |
| S11 | 253 | S9 and (solder\$3 or mask or ligh beam)                                   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>10:58 |
| S12 | 230 | S9 and (solder\$3 or ligh beam)   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>10:58 |

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| S13 | 233 | S9 and (solder\$3 or light beam)            | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>10:59 |
| S14 | 256 | S9 and (solder\$3 or mask or light beam)    | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>10:59 |
| S15 | 10  | (soldering using light beam)                | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>11:00 |
| S16 | 58  | (light beam soldering)                      | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>11:05 |
| S17 | 8   | (light\$beam soldering)                     | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>11:06 |
| S18 | 256 | S14 and (molded interconnect device or MID) | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>12:44 |

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| S19 | 256 | S14 and (molded interconnect device)                                      | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>12:44 |
| S20 | 0   | S16 and S18   | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>12:44 |
| S21 | 431 | S9 and (connector or conduct\$3 or solder or mask or ligh beam or shield) | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>14:29 |
| S22 | 220 | S21 and (solder\$3)   | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>14:29 |
| S23 | 228 | S21 and (solder\$3 or iron)   | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>14:35 |
| S24 | 355 | (228/135).OCLS.   | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR  | OFF | 2009/10/08<br>15:14 |

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| S25 | 523 | (molded interconnect device)  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>15:18 |
| S26 | 0   | S16 and S25   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>15:18 |
| S27 | 1   | S24 and (light beam solder\$3)  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>15:19 |
| S28 | 107 | S24 and (light beam or solder\$3 or laser or iron)                                    | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>15:23 |
| S29 | 176 | S24 and (connector\$2 or connecting or connection\$2 or mask or shield or contact\$2) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>15:24 |
| S30 | 90  | S28 and S29   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/08<br>15:24 |

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| S31 | 7421 | (439/394,578,492,67,630,660,866,931,59,60,77),COLS. | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR  | OFF | 2009/10/08<br>15:37 |
| S32 | 0    | S31 and (light beam solder\$3)                      | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>15:38 |
| S33 | 12   | S31 and (light beam)                                | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>15:38 |
| S34 | 3073 | S31 and (solder\$3)                                 | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>15:39 |
| S35 | 9    | S31 and (molded interconnect device)                | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>15:39 |
| S36 | 5    | S33 and S34   | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>15:39 |

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| S37 | 0    | S35 and S36  | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>15:40 |
| S38 | 6222 | (219/121.6,121.63,121.64,121.65,121.66,121.78,148).CCLS. | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR  | OFF | 2009/10/08<br>16:14 |
| S39 | 1019 | S38 and (light beam or solder\$3)                        | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>16:15 |
| S40 | 541  | S38 and (light beam)                                     | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>16:15 |
| S41 | 554  | S38 and (solder\$3)                                      | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>16:16 |
| S42 | 76   | S40 and S41  | US_PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>16:16 |

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| S43 | 523   | S9 and (connector or conduct\$3 or mask or ligh beam or shield or iron or connection\$2 or connecting or lines or contact\$2 or molded interconnect device or MID or coaxial or jig)  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>16:21 |
| S44 | 75    | S42 and (connector or conduct\$3 or mask or ligh beam or shield or iron or connection\$2 or connecting or lines or contact\$2 or molded interconnect device or MID or coaxial or jig) | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/08<br>16:22 |
| S45 | 355   | (228/135).COLS.   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR  | OFF | 2009/10/13<br>08:27 |
| S46 | 0     | S45 and (soldering with mask and @ay<"2004")  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/13<br>08:27 |
| S47 | 2     | S45 and (soldering with mask)   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON  | 2009/10/13<br>08:28 |
| S48 | 53254 | ("228").CLAS.   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR  | OFF | 2009/10/13<br>08:29 |

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| S49 | 138 | S48 and (soldering with mask and @ay< "2004") | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ | ON | 2009/10/13<br>08:29 |
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10/13/2009 6:33:28 PM

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